

REMARKS

Careful consideration has been given by the applicants to the Examiner's comments and rejection of the claims, as set forth in the outstanding Office Action, and favorable reconsideration and allowance of the application, as amended, is earnestly solicited.

Applicants note the Examiner's rejection of Claims 1-12 under 35 U.S.C. §103(a) as being unpatentable over Japanese Publication JP 11-107,112, as detailed in the Office Action.

Concerning the foregoing, applicants note that in view of similar prior art publications, the parent application, which has matured into U.S. Patent No. 6,488,198 B1, has been deemed to be directed to clearly patentable subject matter.

In essence, although in general terms the Japanese publication, JP 11-107,112 discloses a woven fiberglass sheet suitable for use in laminating processes, such as circuit boards, the applications of closed woven fiberglass sheeting is generally known in the technology, and it is the specific closeness and arrangements of the warp and weft threads or strands, which enable the support of the circuit pads, so that during the lamination process there is avoided any damaging of the pads, which would have an adverse effect on the service life of the printed circuit structure.

As can be clearly ascertained from the Japanese publication, the latter is specifically directed to larger sized spacings between the various cross printed wire boards in which the spacings are in excess of 0.7 mil and further increase to a range of up to 1.3 mil. This is clearly contrary to the present arrangement and laminate support structure wherein such large sizes would cause the pads to be damaged during the laminating process, particularly inasmuch as the wire diameters are generally 0.7 or preferably even smaller in size down to approximately 0.2 mils. This small scale is considered to be inapplicable in accordance

with the Japanese publications, which is specifically directed to larger sizes in excess of 0.7 mils, and, consequently, would not be applicable to the present structures. Accordingly, in order to be directed to the much smaller wire diameters and to prevent the spacing from becoming excessive so as to cause potential damage to the pads, the spacing is limited to the wire diameters or even smaller, such as within the range of approximately 0.2 to 0.7 mils.

Consequently, in order to clearly and unambiguously distinguish over the art, applicants have cancelled Claims 2, 4, 8 and 10 without prejudice or disclaimer, and have incorporated the limitations of Claims 2 and 4 into Claim 1; and the limitations of Claims 8 and 10 into Claim 7, respectively.

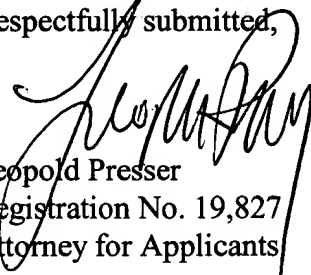
This, in essence, clearly defines the claims to be in the specific ranges in which the invention is intended to be utilized in the lamination process of wire bonding a circuit device.

Neither the prior art cited by the Examiner, as represented by the Japanese publication, nor any other art known to the applicants set forth these particular dimensional limitations, which are deemed to define a structure providing the inherent advantages not disclosed nor suggested in any of the prior art, irrespective as to whether the latter is considered singly or in combination.

In view of the foregoing, and also on the basis of all of the previously submitted arguments, which set forth the specific advantages and distinctions over the art, the present application is deemed to be in substantial condition for allowance, and the early and favorable reconsideration thereof and issuance of the Notice of Allowance by the Examiner is earnestly solicited.

However, in the event that the Examiner has any queries concerning the instantly submitted Amendment, applicants' attorney respectfully requests that he be accorded the courtesy of possibly a telephone conference to discuss any matters in need of attention.

Respectfully submitted,



Leopold Presser
Registration No. 19,827
Attorney for Applicants

SCULLY, SCOTT, MURPHY & PRESSER
400 Garden City Plaza – Suite 300
Garden City, New York 11530
(516) 742-4343

LP:jy